

MA3U749

Silicon epitaxial planar type (cathode common)

For switching mode power supply

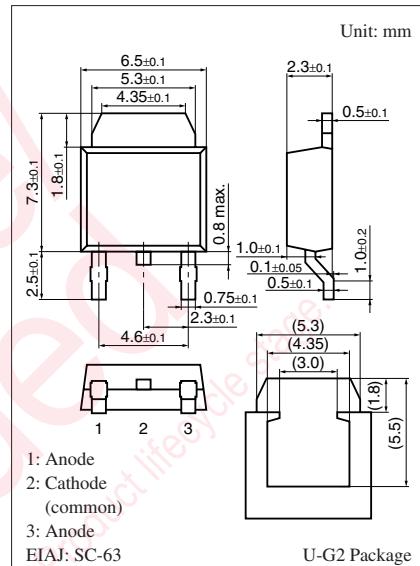
■ Features

- Low forward voltage V_F
- Cathode-common dual type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	40	V
Forward current (Average)	$I_{F(AV)}$	5	A
Non-repetitive peak forward surge current *	I_{FSM}	40	A
Junction temperature	T_j	-40 to +125	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +125	$^\circ\text{C}$

Note) *: Half sine wave; 10 ms/cycle



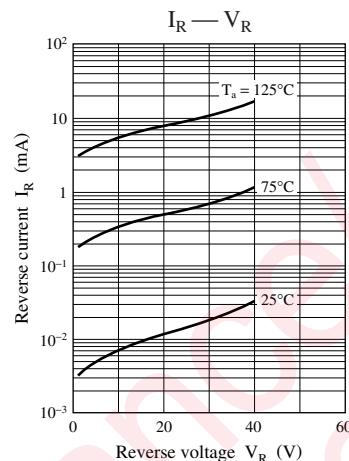
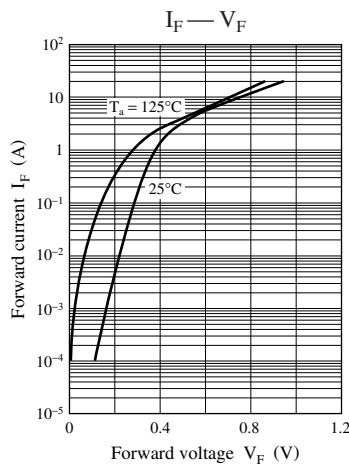
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 2.5 \text{ A}, T_C = 25^\circ\text{C}$			0.55	V
Reverse current	I_R	$V_R = 40 \text{ V}, T_C = 25^\circ\text{C}$			1.0	mA
Thermal resistance (j-c) *	$R_{th(j-c)}$				12.5	$^\circ\text{C}/\text{W}$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. *: $T_C = 25^\circ\text{C}$



Maintained and Discontinued

Maintenance/Discontinued includes following four Product lifecycle stage.

planed maintenance type

planed discontinued type

discontinued type

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